

# HEF4518B

## Dual BCD counter

Rev. 7 — 21 November 2011

Product data sheet

## 1. General description

The HEF4518B is a dual 4-bit internally synchronous BCD counter. The counter has an active HIGH clock input ( $nCP0$ ) and an active LOW clock input ( $n\overline{CP1}$ ), buffered outputs from all four bit positions ( $nQ0$  to  $nQ3$ ) and an active HIGH overriding asynchronous master reset input ( $nMR$ ). The counter advances on either the LOW-to-HIGH transition of the  $nCP0$  input if  $n\overline{CP1}$  is HIGH or the HIGH-to-LOW transition of the  $n\overline{CP1}$  input if  $nCP0$  is LOW. Either  $nCP0$  or  $n\overline{CP1}$  may be used as the clock input to the counter and the other clock input may be used as a clock enable input. A HIGH on  $nMR$  resets the counter ( $nQ0$  to  $nQ3 = \text{LOW}$ ) independent of  $nCP0$ ,  $n\overline{CP1}$ . Schmitt trigger action in the clock input makes the circuit highly tolerant of slower clock rise and fall times.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

## 2. Features and benefits

- Tolerant of slow clock rise and fall times
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

## 3. Applications

- Multistage synchronous counting
- Multistage asynchronous counting
- Frequency dividers

## 4. Ordering information

**Table 1. Ordering information**

All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$

Type number	Package		Version
	Name	Description	
HEF4518BP	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
HEF4518BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1



5. Functional diagram

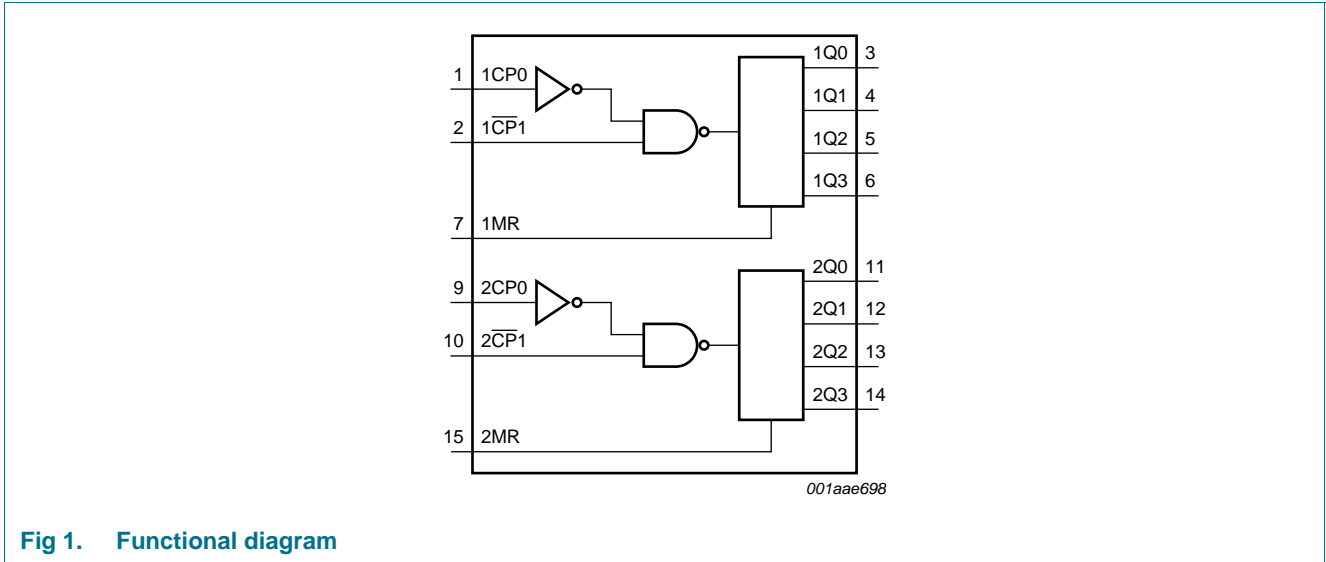


Fig 1. Functional diagram

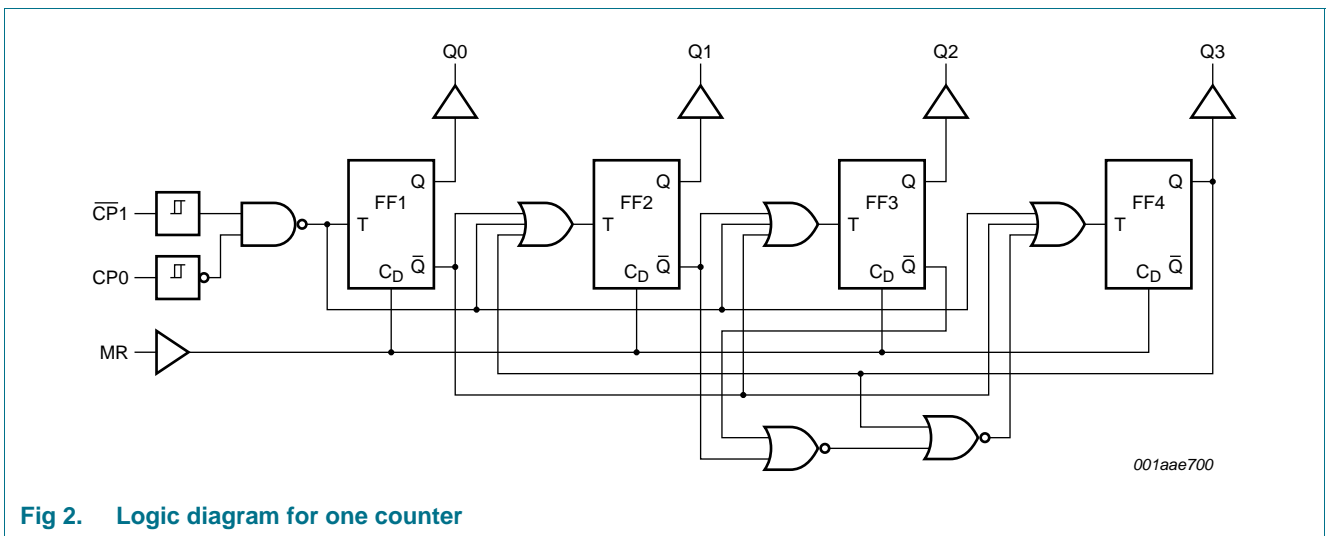
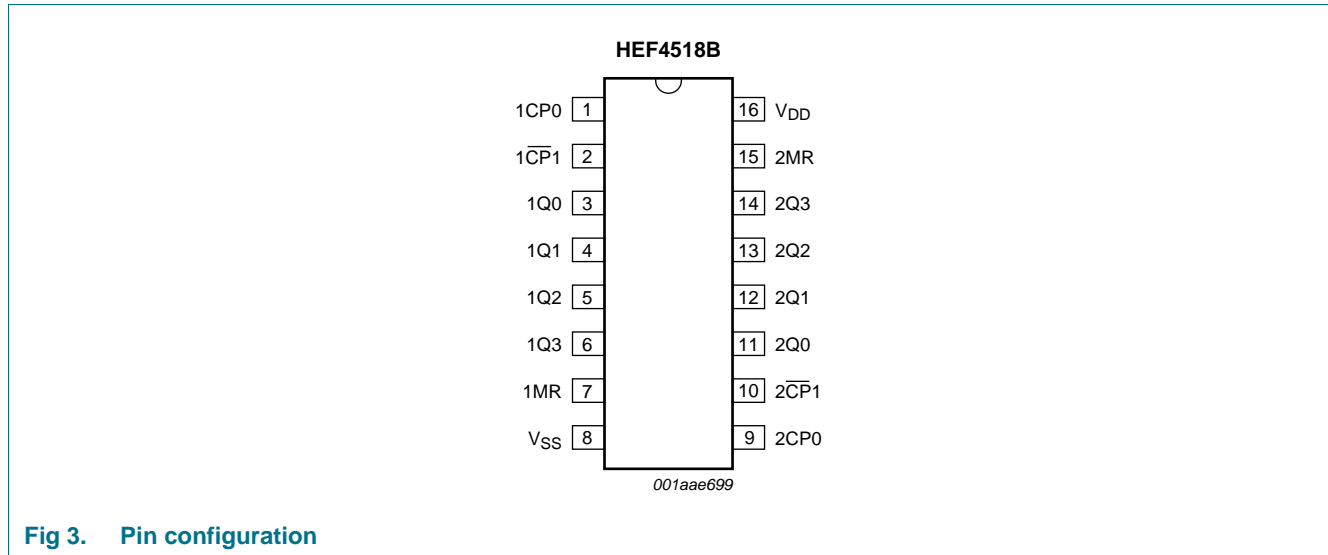


Fig 2. Logic diagram for one counter

## 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

**Table 2. Pin description**

Symbol	Pin	Description
1CP0, 2CP0	1, 9	clock input (LOW-to-HIGH triggered)
1CP1, 2CP1	2, 10	clock input (HIGH-to-LOW triggered)
1Q0, 2Q0	3, 11	output
1Q1, 2Q1	4, 12	output
1Q2, 2Q2	5, 13	output
1Q3, 2Q3	6, 14	output
1MR, 2MR	7, 15	master reset input
V <sub>DD</sub>	16	supply voltage
V <sub>SS</sub>	8	ground supply voltage

## 7. Functional description

Table 3. Function table<sup>[1]</sup>

nCP0	nCP1	nMR	Mode
↑	H	L	counter advances
L	↓	L	counter advances
↓	X	L	no change
X	↑	L	no change
↑	L	L	no change
H	↓	L	no change
X	X	H	nQ0 to nQ3 = LOW

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; ↑ = positive-going transition; ↓ = negative-going transition.

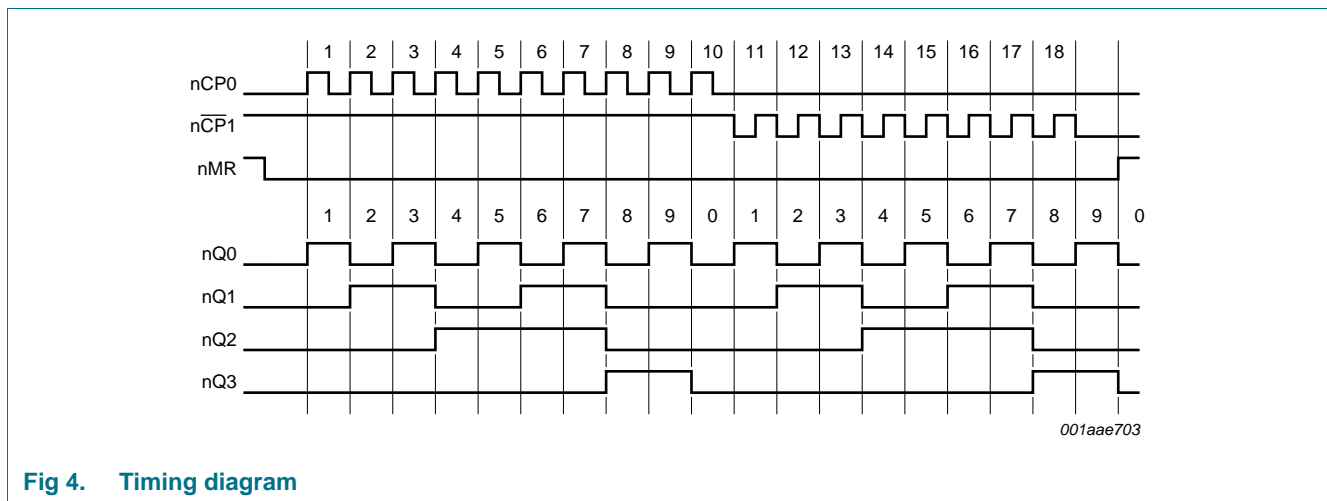


Fig 4. Timing diagram

## 8. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		-0.5	+18	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{DD} + 0.5\text{ V}$	-	$\pm 10$	mA
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{DD} + 0.5\text{ V}$	-	$\pm 10$	mA
$I_{I/O}$	input/output current		-	$\pm 10$	mA
$I_{DD}$	supply current		-	50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$T_{amb}$	ambient temperature		-40	+85	°C
$P_{tot}$	total power dissipation	DIP16 package	[1]	750	mW
		SO16 package	[2]	500	mW
$P$	power dissipation	per output	-	100	mW

[1] For DIP16 package:  $P_{tot}$  derates linearly with 12 mW/K above 70 °C.

[2] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

## 9. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	supply voltage		3	-	15	V
$V_I$	input voltage		0	-	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5\text{ V}$	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10\text{ V}$	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15\text{ V}$	-	-	0.08	$\mu\text{s/V}$

## 10. Static characteristics

**Table 6. Static characteristics**

$V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$  unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ °C}$		$T_{amb} = 25\text{ °C}$		$T_{amb} = 85\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\ \mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\ \mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V

**Table 6. Static characteristics ...continued**  
 $V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$  unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ }^\circ\text{C}$		$T_{amb} = 25\text{ }^\circ\text{C}$		$T_{amb} = 85\text{ }^\circ\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.52	-	-0.44	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.3	-	-1.1	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-3.6	-	-3.0	-	-2.4	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.52	-	0.5	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.3	-	1.1	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	3.6	-	3.0	-	2.4	-	mA
$I_I$	input leakage current	$V_{DD} = 15\text{ V}$	15 V	-	$\pm 0.3$	-	$\pm 0.3$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	$I_O = 0\text{ A}$	5 V	-	20	-	20	-	150	$\mu\text{A}$
			10 V	-	40	-	40	-	300	$\mu\text{A}$
			15 V	-	80	-	80	-	600	$\mu\text{A}$
$C_I$	input capacitance		-	-	-	7.5	-	-	pF	

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**  
 $V_{SS} = 0\text{ V}$ ;  $T_{amb} = 25\text{ }^\circ\text{C}$ ; for test circuit see [Figure 6](#); unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Typ	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	nCP0, nCP1 to nQn; see <a href="#">Figure 5</a>	5 V	<a href="#">[1]</a> $93\text{ ns} + (0.55\text{ ns/pF})C_L$	-	120	240	ns
			10 V	$44\text{ ns} + (0.23\text{ ns/pF})C_L$	-	55	110	ns
			15 V	$32\text{ ns} + (0.16\text{ ns/pF})C_L$	-	40	80	ns
		nMR to nQn; see <a href="#">Figure 5</a>	5 V	$48\text{ ns} + (0.55\text{ ns/pF})C_L$	-	75	150	ns
			10 V	$24\text{ ns} + (0.23\text{ ns/pF})C_L$	-	35	70	ns
			15 V	$17\text{ ns} + (0.16\text{ ns/pF})C_L$	-	25	50	ns
$t_{PLH}$	LOW to HIGH propagation delay	nCP0, nCP1 to nQn; see <a href="#">Figure 5</a>	5 V	<a href="#">[1]</a> $93\text{ ns} + (0.55\text{ ns/pF})C_L$	-	120	240	ns
			10 V	$44\text{ ns} + (0.23\text{ ns/pF})C_L$	-	55	110	ns
			15 V	$32\text{ ns} + (0.16\text{ ns/pF})C_L$	-	40	80	ns
$t_t$	transition time	nQn; see <a href="#">Figure 5</a>	5 V	<a href="#">[1]</a> $10\text{ ns} + (1.00\text{ ns/pF})C_L$	-	60	120	ns
			10 V	$9\text{ ns} + (0.42\text{ ns/pF})C_L$	-	30	60	ns
			15 V	$6\text{ ns} + (0.28\text{ ns/pF})C_L$	-	20	40	ns

**Table 7. Dynamic characteristics ...continued**

$V_{SS} = 0\text{ V}$ ;  $T_{amb} = 25\text{ °C}$ ; for test circuit see [Figure 6](#); unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Typ	Max	Unit
$t_w$	pulse width	nCP0 input LOW; minimum width; see <a href="#">Figure 5</a>	5 V		60	30	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
		nCP1 input HIGH; minimum width; see <a href="#">Figure 5</a>	5 V		60	30	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
		nMR input HIGH; minimum width; see <a href="#">Figure 5</a>	5 V		30	15	-	ns
			10 V		20	10	-	ns
			15 V		16	8	-	ns
$t_{rec}$	recovery time	nMR input; see <a href="#">Figure 5</a>	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
$t_{su}$	set-up time	nCP0 to nCP1; see <a href="#">Figure 5</a>	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
		nCP1 to nCP0; see <a href="#">Figure 5</a>	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
$f_{max}$	maximum frequency	nCP0, nCP1; see <a href="#">Figure 5</a>	5 V		8	16	-	MHz
			10 V		15	30	-	MHz
			15 V		20	40	-	MHz

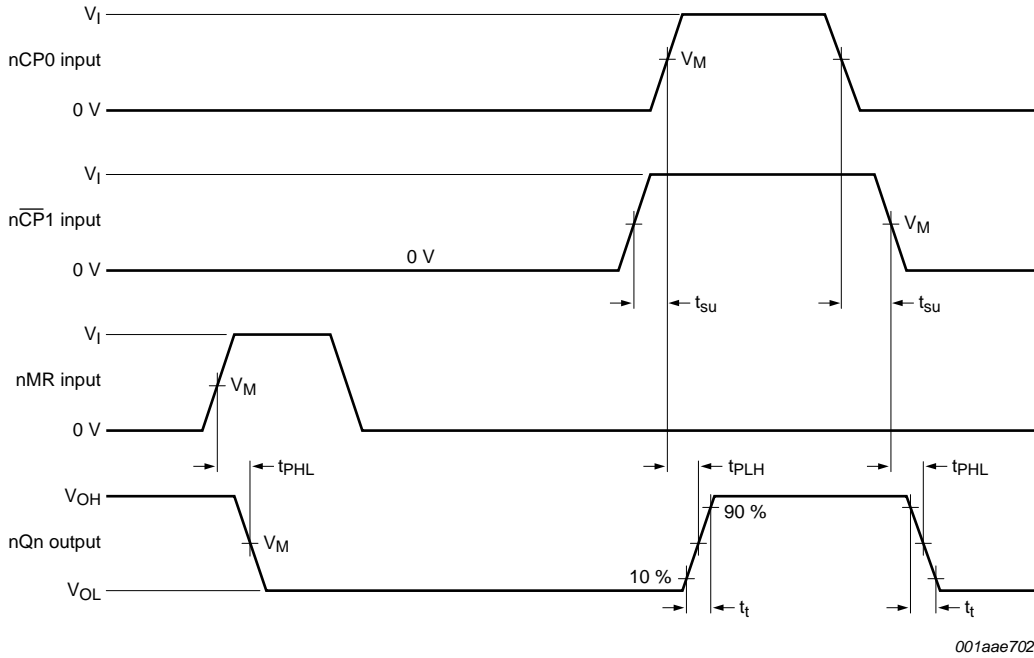
[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown ( $C_L$  in pF).

**Table 8. Dynamic power dissipation  $P_D$**

$P_D$  can be calculated from the formulas shown.  $V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ °C}$ .

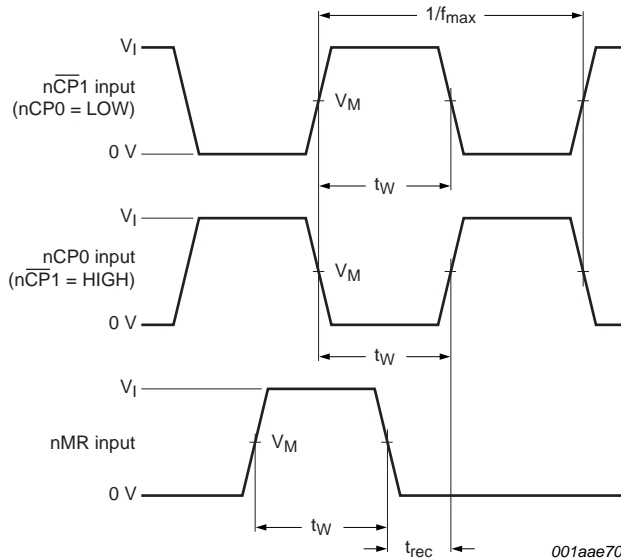
Symbol	Parameter	$V_{DD}$	Typical formula for $P_D$ ( $\mu\text{W}$ )	Where:
$P_D$	dynamic power dissipation	5 V	$P_D = 750 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	$f_i$ = input frequency in MHz;
		10 V	$P_D = 3300 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	$f_o$ = output frequency in MHz;
		15 V	$P_D = 8000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	$C_L$ = output load capacitance in pF;
				$V_{DD}$ = supply voltage in V;
				$\Sigma(f_o \times C_L)$ = sum of the outputs.

12. Waveforms



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a. nCP0 and nCP1 set-up times, propagation delays and output transition times



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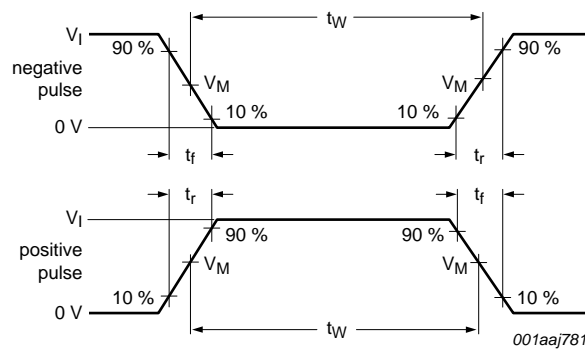
b. nMR recovery time, minimum nCP0, nCP1, and nMR pulse widths and maximum frequency

Measurement points are given in table [Table 9](#).

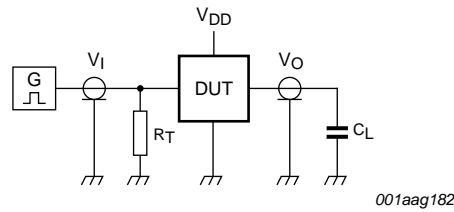
The logic levels  $V_{OH}$  and  $V_{OL}$  are typical output voltage levels that occur with the output load.

Fig 5. Waveforms showing measurements for switching times





a. Input waveforms



b. Test circuit

Test data is given in [Table 9](#).

Definitions for test circuit:

DUT = Device Under Test;

$C_L$  = Load capacitance including jig and probe capacitance;

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

Fig 6. Test circuit for switching times

Table 9. Measurement points and test data

Supply voltage	Input			Load
	$V_I$	$V_M$	$t_r, t_f$	$C_L$
5 V to 15 V	$V_{DD}$	$0.5V_I$	$\leq 20$ ns	50 pF

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

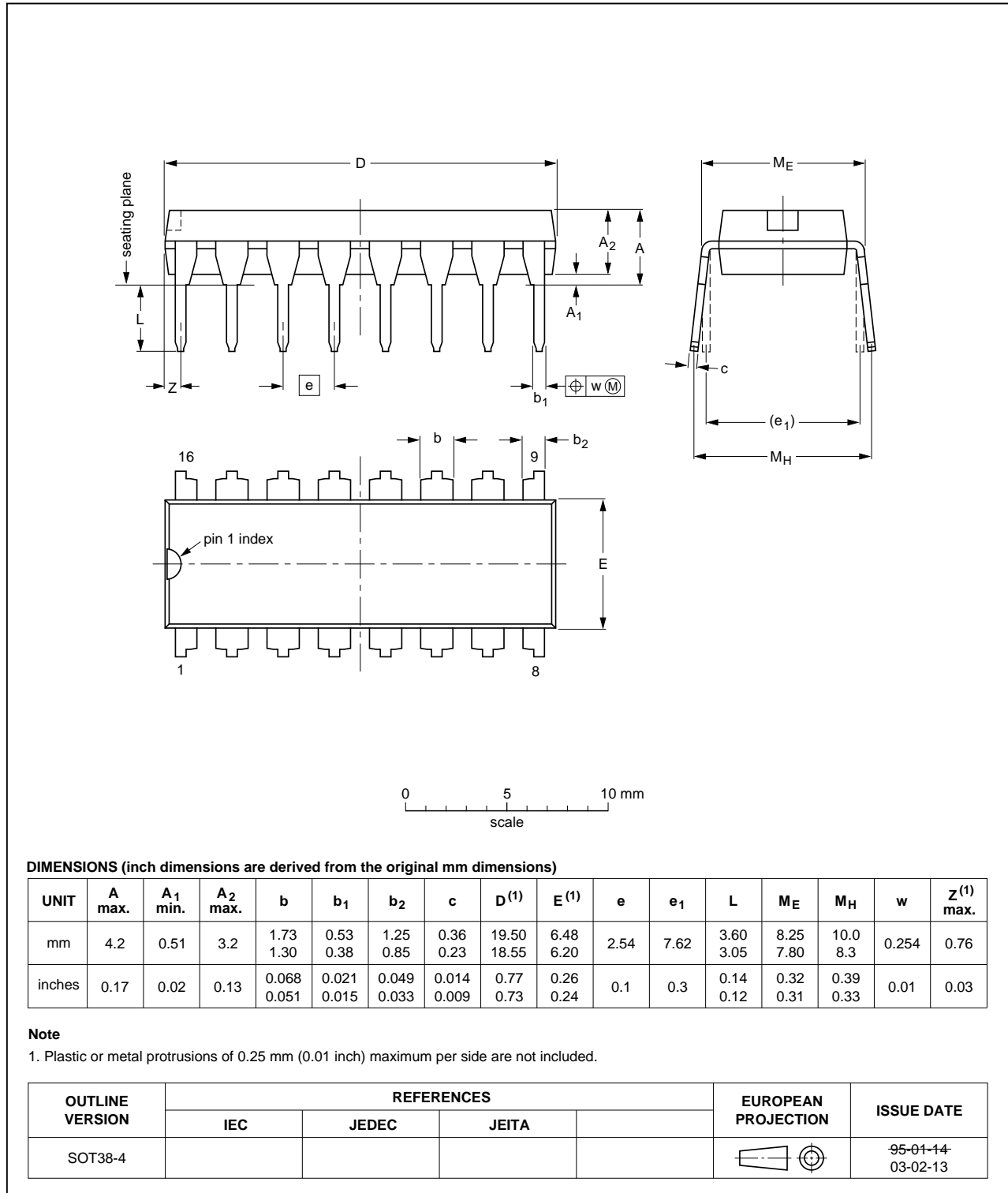


Fig 7. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

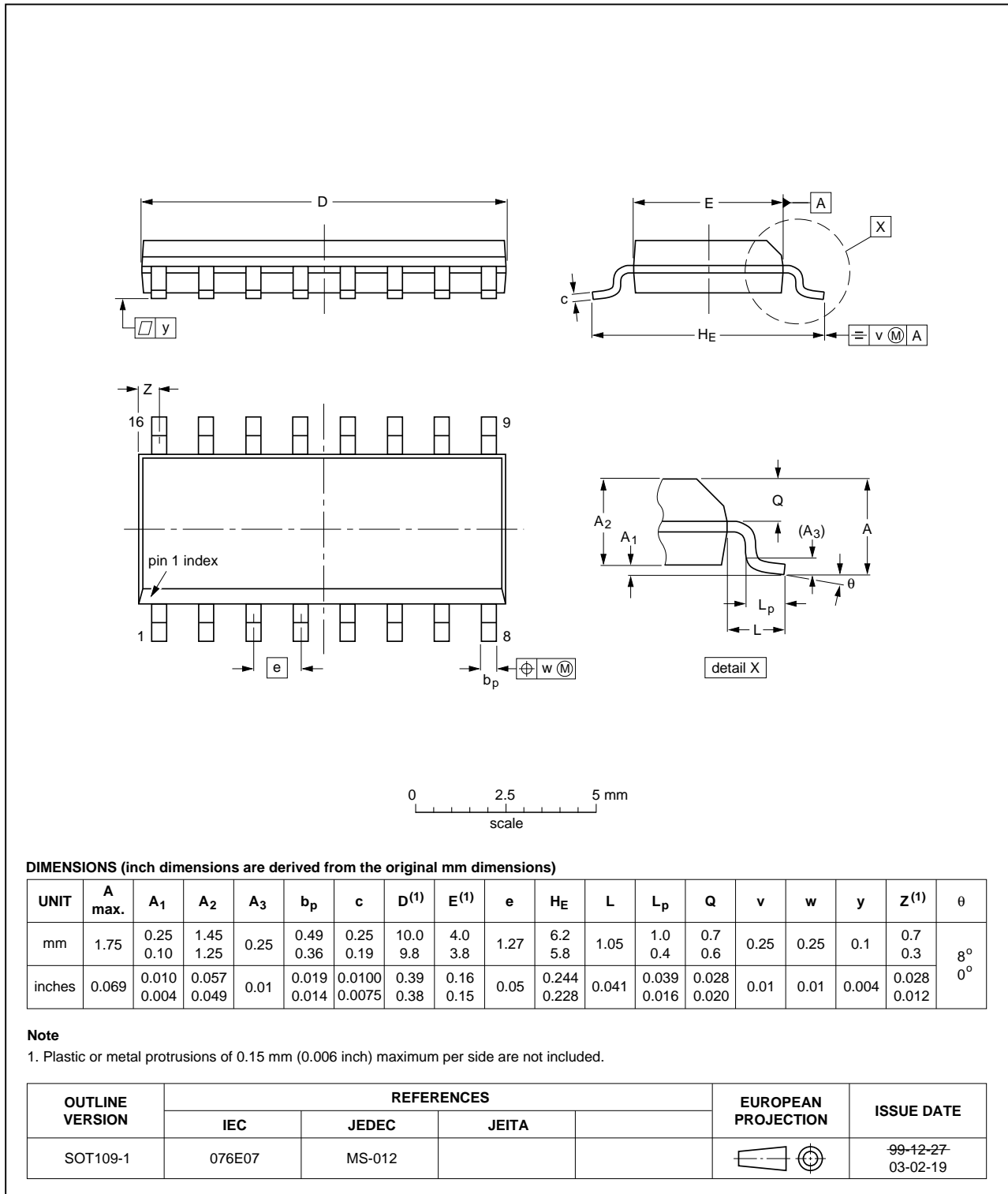


Fig 8. Package outline SOT109-1 (SO16)

## 14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4518B v.7	20111121	Product data sheet	-	HEF4518B v.6
Modifications:	<ul style="list-style-type: none"><li>• <a href="#">Table 6</a>: I<sub>OH</sub> minimum values changed to maximum</li><li>• <a href="#">Figure 6</a>: added "DUT = Device Under Test"</li></ul>			
HEF4518B v.6	20091210	Product data sheet	-	HEF4518B v.5
HEF4518B v.5	20090727	Product data sheet	-	HEF4518B v.4
HEF4518B v.4	20090703	Product data sheet	-	HEF4518B_CNV v.3
HEF4518B_CNV v.3	19950101	Product specification	-	HEF4518B_CNV v.2
HEF4518B_CNV v.2	19950101	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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